LIGHTWAVELOGIC® Faster by Design

Are electro-optic polymers two sides of one coin? Michael Lebby, CEO

NASDAQ

LWLG

EPIC Technology Meeting: Microelectronics and photonics – two sides of one coin. November 2023

Safe Harbor

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The information in this presentation may contain forward-looking statements within the meaning of the Private Securities Litigation Reform Act of 1995. You can identify these statements by use of the words "may," "will," "should," "plans," "explores," "expects," "anticipates," "continue," "estimate," "project," "intend," and similar expressions. Forward-looking statements involve risks and uncertainties that could cause actual results to differ materially from those projected or anticipated. These risks and uncertainties include, but are not limited to, general economic and business conditions, effects of continued geopolitical unrest and regional conflicts, competition, changes in technology and methods of marketing, delays in completing various engineering and manufacturing programs, changes in customer order patterns, changes in product mix, continued success in technological advances and delivering technological innovations, shortages in components, production delays due to performance quality issues with outsourced components, and various other factors beyond the Company's control.

Two sides of one coin...

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Two sides of one coin...

- Much the same
- Cut from the same cloth
- Double-edged sword
- Two peas in a pod
- Adjacent
- Apples and oranges
- Two of a kind
- In the same league
- On equal footing
- Interchangeable
- Parallel
- Same same, but different
- Indistinguishable





...different ways of looking at or dealing with the same situation...

Are the sides independent or symbiotic?

Microelectronics...

- Microelectronics is the manufacture (or microfabrication) of very small electronic designs and components.
- These devices are typically made from semiconductor materials in *silicon* foundries
- Many components are available in a microelectronic equivalent.
 These include transistors, capacitors, inductors, resistors, diodes and, insulators and
 - conductors etc.
- Unique wiring techniques such as wire bonding, flip chip bumping are also often used because of the unusually small size of the components, leads and pads.

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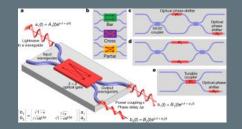


...micro-digital integrated circuits for electronics...

Photonics...

- A photonic integrated circuit (*PIC*) is a microchip containing *two or more photonic components* which form a functioning circuit.
- PIC technology detects, generates, transports, and processes light.
 PICs utilize photons (or particles of light)
- A PIC provides functions for information signals imposed on optical wavelengths typically in the visible spectrum or near infrared (850–1650 nm).





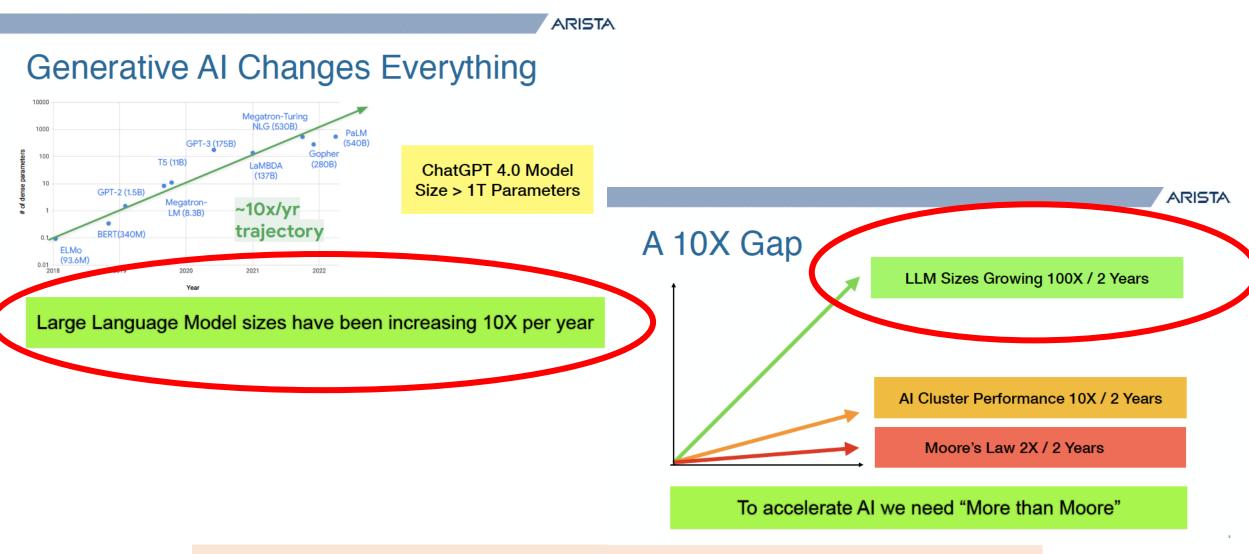
...Photonics integrated circuit (PIC) 2 or more components...

Market Dynamics...

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New frontiers in electronics and photonics



G-AI is driving new frontiers in both electronics and photonics

General-AI market growing quickly

Worldwide G-AI and Non-G-AI Server Infrastructure Forecast (\$M) \$40,000 \$35.000 \$30,000 \$25.000 \$23,674 \$20,000 \$15,000 \$10.000 \$10,988 \$5,000 \$8,203 \$5,466 \$2,946 \$0 2022 2023 2024 2025 2026 G-Al Other Al Source: IDC Estimated CAGR for "AI-Transceivers" alone is 44%

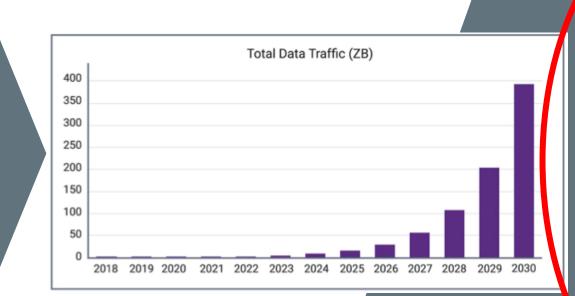


The driver for upgrading transceiver optics in the datacenter and optical network...

~20% of G-AI data center capex is expected to be 800G transceivers (\$3B in 2026)

The importance of photonics in communications





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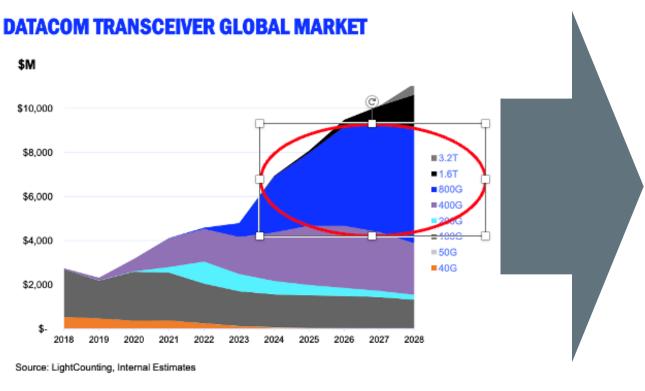
The growth driver of "communication" is datacom...

...The growth driver of datacom is largely Generative AI

The twin enablers of G-AI are photonics and GPUs

Datacom \rightarrow Generative AI \rightarrow Electronics (GPU) and photonics

The importance of photonics in communications



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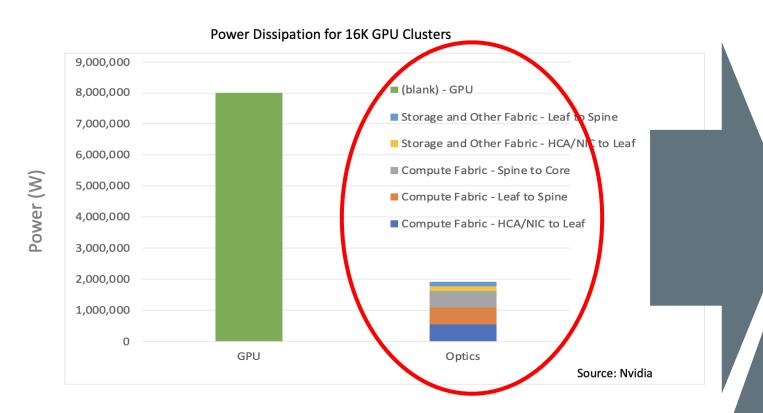
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800Gbps and 1600 Gbps transceiver modules

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Need to upgrade in speed, and lower power consumption

Optics is No Longer A "Minor" Contributor to Datacenter G-AI Power Issues



Large language models requires large GPU clusters (ChatGPT 4 training requires ~25,000 GPUs)

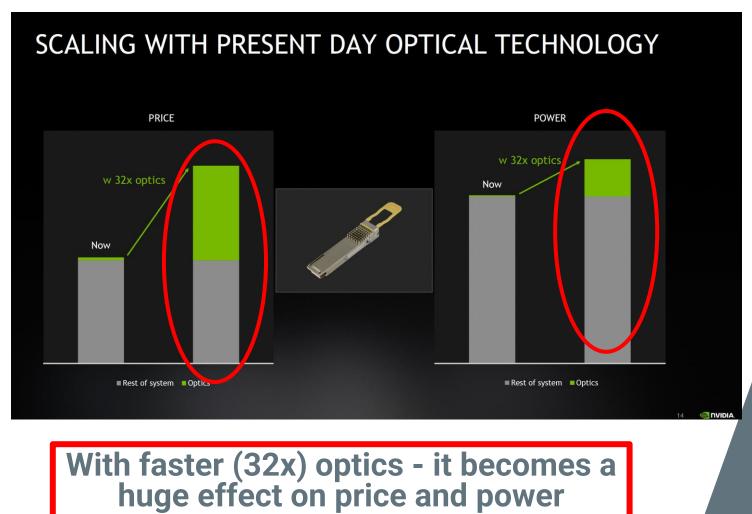
For 16,000 GPU clusters, optics consume ~2MW (equivalent to 4000 GPUs) – source: Nvidia, CIOE, Song, 2023)

Source: Silicon Photonics Solutions for Al/Data Center Applications Rang-Chen Yu, Dong Pan SiFotonics Technologies, ECOC 2023

Power dissipation for AI cluster optics showing optical network power dissipation share increasing...

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General-AI market growing quickly



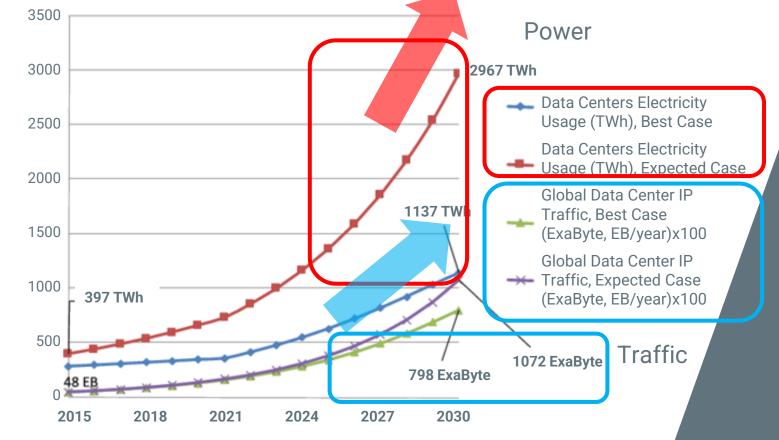
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Datacenter photonics needs to improve quickly....

The Achilles Heel

Existing solutions require excessive amounts of power to scale

Traffic ExaByte & Electricity Usage (TWh) of Data Centers 2015-2030



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Data center power use is growing exponentially with increased traffic levels - the Achilles Heel and a major challenge for data centers and service providers

How can photonics help?

Role of photonics as part of the solution

Key Requirements for Optics at AI Scale

Reliability

Need two orders of improvement to single-digit FITS per Terabit

Power Efficiency

Saving 10 pJ/Bit at 2.5 Exabit/sec equals 25 Megawatts

Cost per Bit

Need to drive from double-digit to single cents/Gigabit.

Progress is being made on all of these fronts, but progress needs to be accelerated

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How to Reduce Optics Power

1. Use Linear Drive Interface

Eliminates DSP/CDR power and cost

2. Use lower power modulators

Lower drive voltage, lower insertion losses

3. Use higher efficiency lasers with better coupling

Laser efficiency makes a major difference in overall power

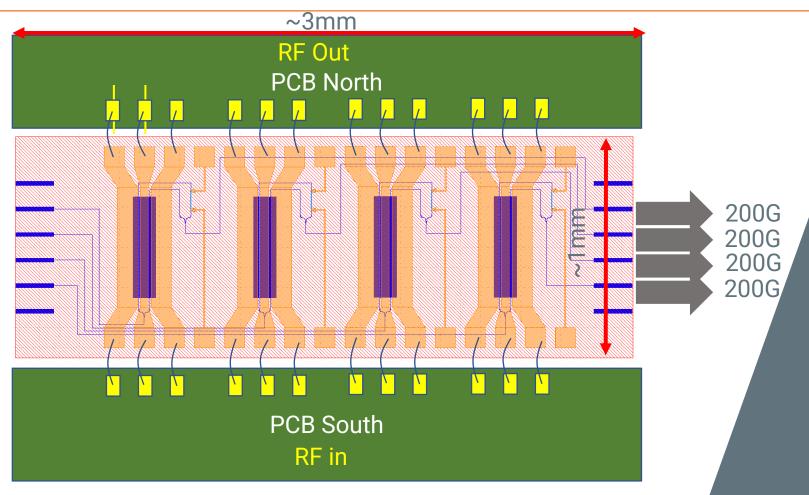
In combination these reduce optics power from 15 pJ/Bit to 5 pJ/Bit, a reduction of 10 pJ/Bit

Arista wish... Arista wish...

Both electronics and photonics needs to improve... ...especially modulators

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Modulators will be part of the solution



- Optical 4 channel Polymer PIC layout with Mach Zehnder Interferometers (MZI) arrays
- Fiber array to be connected on both East and West side using Edge couplers
- Electrical CPW transmission length ~1mm

*Using EO S21 3dB bandwidths in excess of 150GHz, with the potential for >250GHz

Source: Lightwave Logic (LWLG)

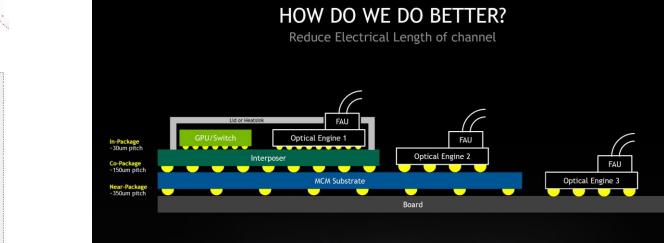


In development \rightarrow 4 channel polymer PIC chip as part of our P²IC platform

Potential for 300G and even 400G per lane*

Packaging will be part of the solution

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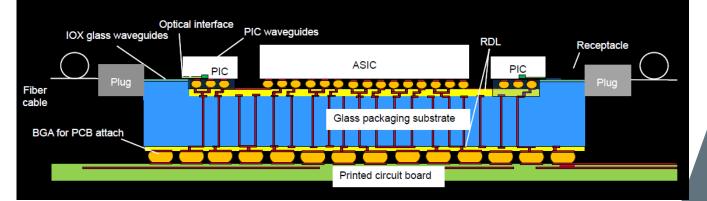
- In-package electrical channels can 10x lower power than near-package or current incumbent solutions
- Adding fiber to the chip must be sub-linear in cost to enable over-provisioned I/O

Packaging is becoming more complex...trend to chip-scale solutions

25.6T System Solutions Show Roadmap to 51.2T 1RU Solutions



Packaging substrate made of glass that enables pick-and place assembly for high-density optical and electrical connections



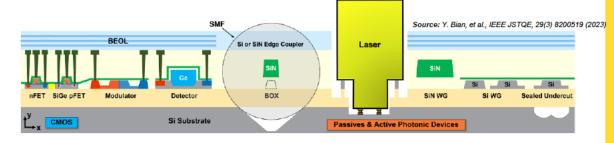
Source: Lightwave Logic (LWLG), Broadcom (2023), Corning, Nvidia

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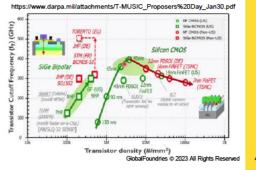
Foundries will be part of the solution

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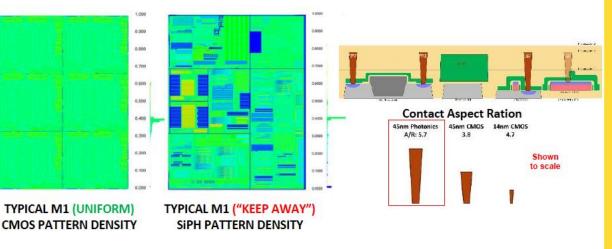
GF Fotonix[™]: Monolithic Silicon Photonics



- Monolithic integration of Photonic Devices with a 45nm class RFCMOS
- 300mm process leveraging immersion lithography
- Advanced immersion lithography SOI WGs and photonic OPC
- Features:
 - Comprehensive photonic passive device library
 - High performance photonic active devices
 - High efficiency sealed undercut (airgap) thermal heaters
 - Micro-ring modulators and dWDM ring filters
 - Freeform design enabled: accepts custom curve-linear GDS
- Packaging: V-groove fiber attach, laser cavity, Cu pillar & TSV
- Test: Wafer level state-of-art optical / electrical test capability



GF Fotonix[™]: Process Window



Process windows are reduced due to keep away zones & high aspect ratios

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Creating PDKs for silicon photonics (that include hybrid technologies)

What we do...

www.unnedinterinterint

Perkinamine[®] Electro-Optic polymers

Our polymers are world-class and proven by third parties

Electro-optic polymers can be used to fabricate optical modulators which enable:



- High material-level thermal and photostability
- Long-term storage and operational durability
- >3x faster modulation than existing products
- ~10x lower power than existing products

EO polymers \rightarrow Fast, stable, reliable, low power consumption, and very small in size



3rd Party Use of Perkinamine[®]

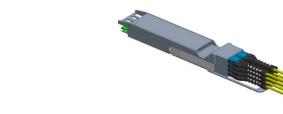
- EO polymer used in different device designs
- Silicon slot, plasmonic slot, plasmonic ring resonator
- All produced world class results*
- Presentations at industry conferences globally

Sources*: Nature Photonics: Resonant plasmonic micro-racetrack modulators with high bandwidth and high temperature tolerance (ETH Zurich, Polariton and LWLG EO polymer material)

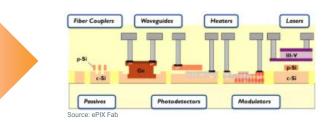
Sources*: KIT, SilOriX, EU Horizon 2020, ETH Zurich, Polariton, CAU University Kiel (post deadline paper published at ECOC2022 using LWLG EO polymers)

Polymer modulator opportunities

Electro-optic polymer modulators for transceivers suppliers



Electro-optic polymer modulators for Silicon Photonic platforms

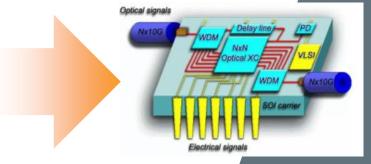


EO polymers enable higher performance data communications

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Electro-optic polymer modulators for "Other"

platforms including optical/quantum computing, HPC, and RF applications



Electro-optic polymer engines for fiber optic communications

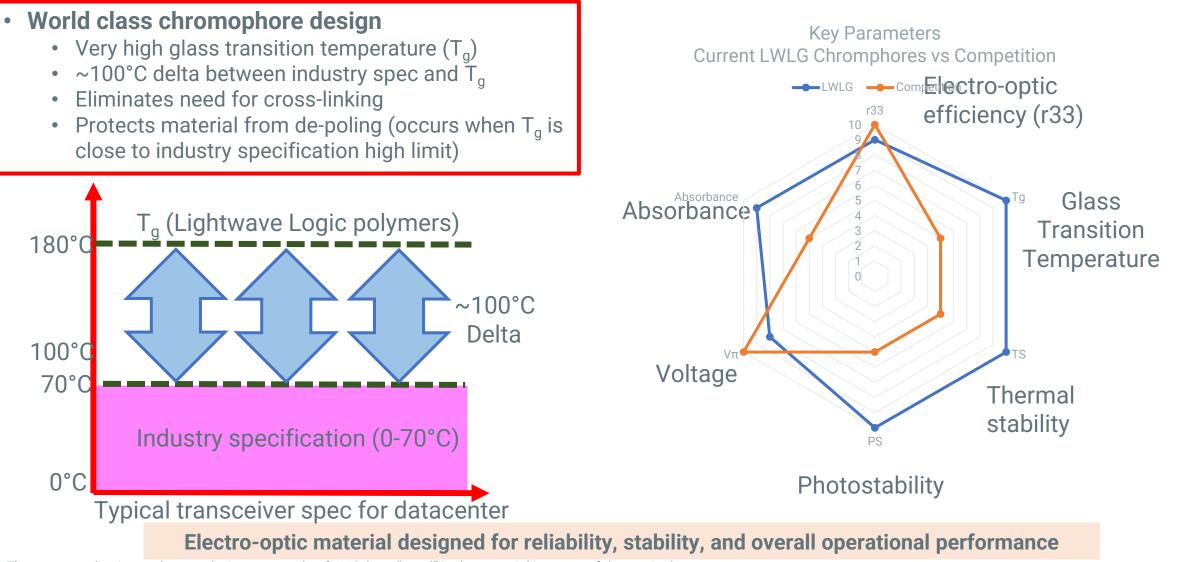
Source: Ethernet Alliance, OSFP MSA, <u>https://www.researchgate.net/figure/Schematic-of-an-on-chip-optical-network-with-various-components-illustrated-including_fig2_239929876</u>, ePIXfab, corning

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Reliability and stability...

Optimized for reliability & stability

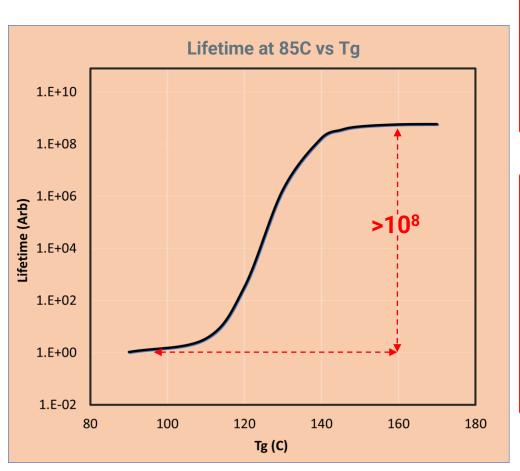




NB: These are qualitative analyses only: i.e. on a scale of 1-10, how "good" is the material in terms of the particular parameter. Source: Lightwave Logic (LWLG), *best estimates of public data

How important is glass transition temperature (T_q) ?





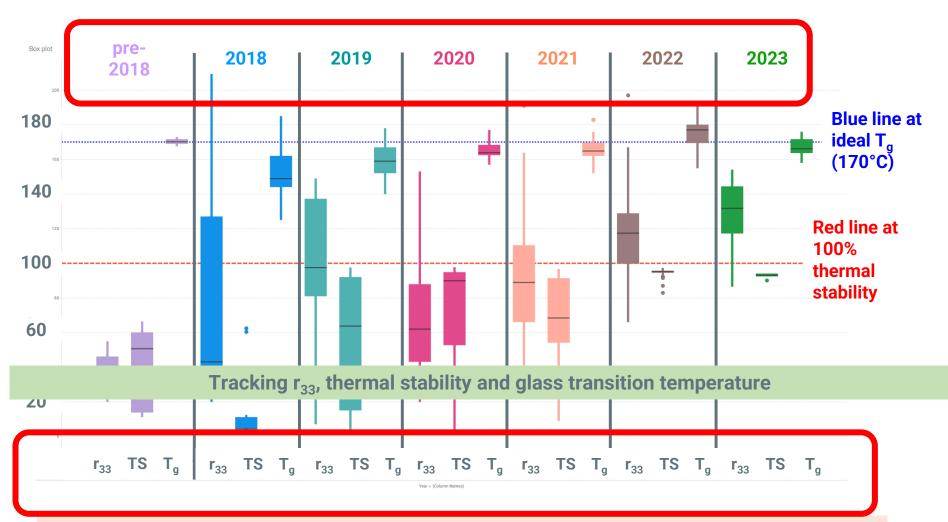
Using the widely quoted Lindsay's time constant formula which is found in **Polymer 48 (2007) 6605-6616** $\ln(\tau/\tau_{\rm P}) = E_{\rm R} \left(1 + \tanh\left[\left(T_{\rm c} - T\right)/D\right]\right) / 2RT + E_{\rm P}/RT$

The thermal lifetime of an EO-polymer material at 85C will increase with increasing Tg

The lifetime at 85°C for a polymer with T_g =160°C is >10⁸ times greater than the lifetime for a polymer with T_g = 90°C Increasing Tg → means much higher lifetime in electro-optic materials

How have EO polymers improved over the last 6 years?

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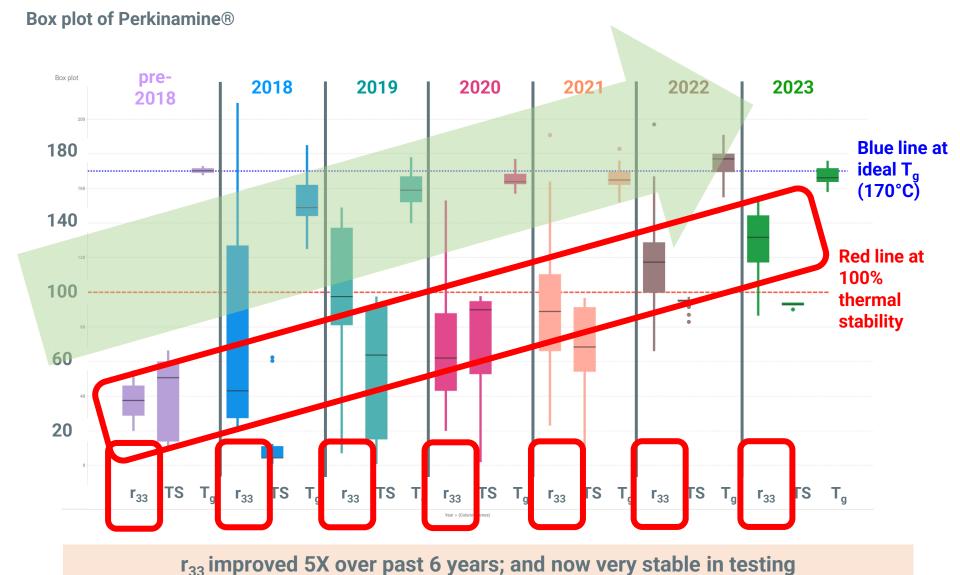
Box plot of Perkinamine®

Tracking r₃₃, thermal stability and glass transition temperature

A box plot or boxplot is a method for graphically demonstrating the locality, spread and skewness groups of numerical data through their quartiles Source: Lightwave Logic (LWLG), *best estimates;

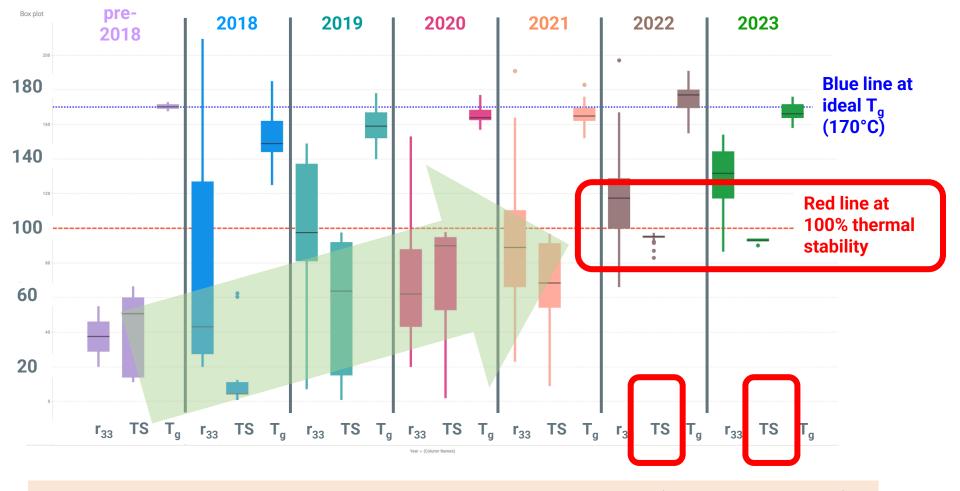
Tracking r₃₃ improvements





Tracking TS (Thermal Stability) improvements

Box plot of Perkinamine®



Super performance of material thermal stability in last 2 years (approaching 100%)

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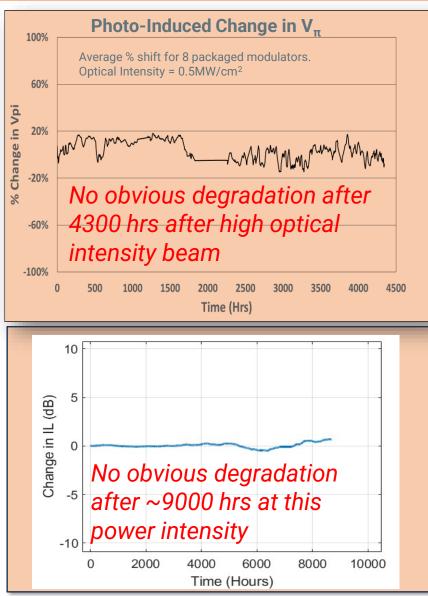
Tracking glass transition temperature (T_g)

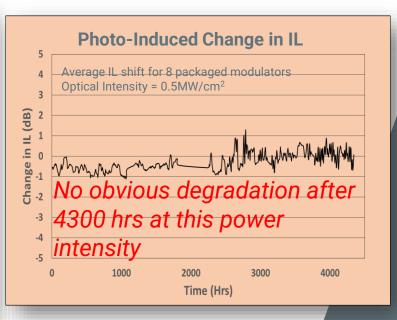
Box plot pre-2022 2023 2018 2019 2020 2021 2018 Blue line at 180 ideal T (170°C) 140 **Red line at** 100% 100 thermal stability 60 20 $\mathbf{T}_{\mathbf{g}}$ \mathbf{T}_{g} $\mathbf{T}_{\mathbf{g}}$ \mathbf{T}_{g} r_{33} TS T_g r_{33} TS T_g r_{33} TS T_g r₃₃ T Т T r₃₃ r₃₃ 33 Tight control of materials with extremely high T_a at 170C

Box plot of Perkinamine®

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Photostability vs Voltage and Insertion Loss



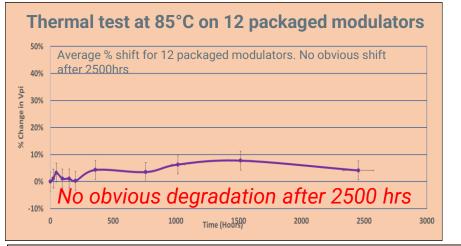


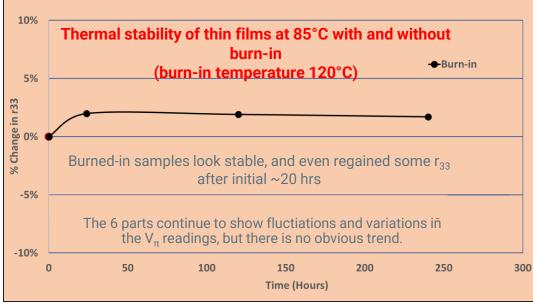
Long and shortterm photostability does not seem to be an issue with LWLG electrooptic chromophores

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Source: Lightwave Logic (LWLG)

Device Thermal Stability (TS) against change in voltage





Thermal stability does not seem to be an issue with LWLG packaged modulators or burn-in against change in r₃₃

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Source: Lightwave Logic (LWLG)

Polymers (organics) on system roadmap



EOM Technology Comparison

Technology	Integration Capability	Bandwidth	Vpi (1)	Insertion Loss (2)	Reliability	HVM (3)
Silicon Photonics	Excellent	Good	High	High	Proven	Now
III-V	Low	Higher	Lower	Low	Proven	Now
TFLN	Low	Very High	Lower	Low	Proven	2024 (E)
вто	New Process	Very High	Low	Low	Proven	2025 (E)
Organic	New Process	Very High	Lowest) Low 🤇	To be Proven	2026 (E)

(1) Tx Drive power is CV^2 -f-dominated

(2) Lower insertion loss reduces laser power

(3) HVM = High volume manufacturing

Lower Vpi Drive Voltage results in significant power reduction

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Our focus is on:

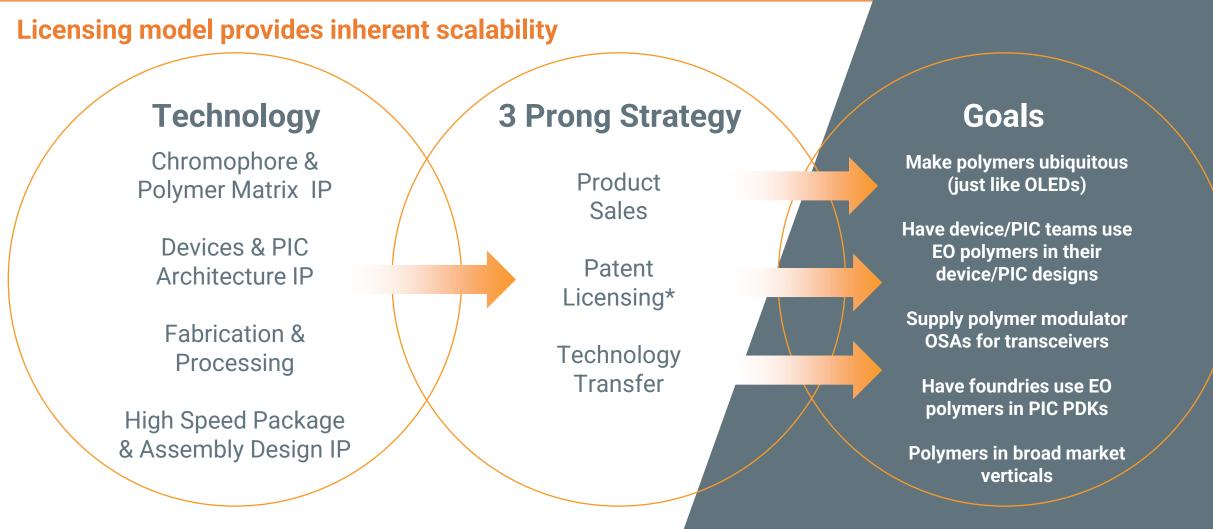
 1) lifetime & reliability
 2) TTM (time to market)

Trying electro-optic polymers...

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Implementing a new technology platform...

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*1st commercial material supply license agreement 2Q23 \rightarrow market acceptance

Two sides of one coin...

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Is microelectronics and photonics two sides of one coin?

- Much the same not really (maybe silicon)
- Cut from the same cloth (maybe silicon)
- Double-edged sword certainly
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- Adjacent certainly
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- In the same league perhaps
- On equal footing not yet, maybe never
- Interchangeable not really
- Parallel not really
- Same, but different perhaps
- Indistinguishable not really



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...different ways of looking at or dealing with the same situation...



Independent or symbiotic?

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Symbiotic relationship...

 One can't live with out the other, and both need each other





...remora fish living on the shark...

Microelectronics and photonics... ...symbiotic



Takeaways

- Symbiotic relationship needs upgrading for both electronics and photonics; however, G-AI is changing the playing field...the opportunity is huge...
- Industry needs higher performance packaging, modulators, lower power, higher speed, more linear electronics...
- EO polymers continue to show technical progress with polymer reliability and stability...
- EO polymer materials can scale today, and we are positioning to have EO polymer modulators scale using foundries/OSATs...



TWAVELOGI

Investor Relations Contact

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IGHTWAVELOGIC® Faster by Design

Thank you for listening

lightwavelogic.com

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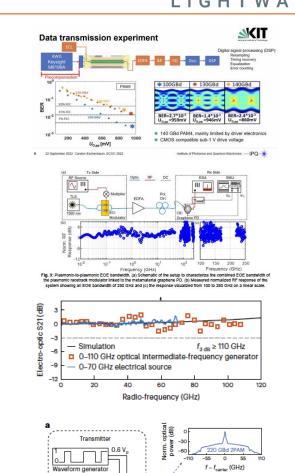
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3rd party verification...

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3rd party use of Perkinamine®

- EO polymer used in different device designs
- Silicon slot, plasmonic slot, plasmonic ring resonator
- All produced world class results*
- Presentations at *industry* conferences



Transmitte

Offline DS

136 GBd 8PAI

60 GBd 4PAM

Sources*: Nature Photonics: Resonant plasmonic micro-racetrack modulators with high bandwidth and high temperature tolerance (ETH Zurich, Polariton and LWLG EO polymer material)

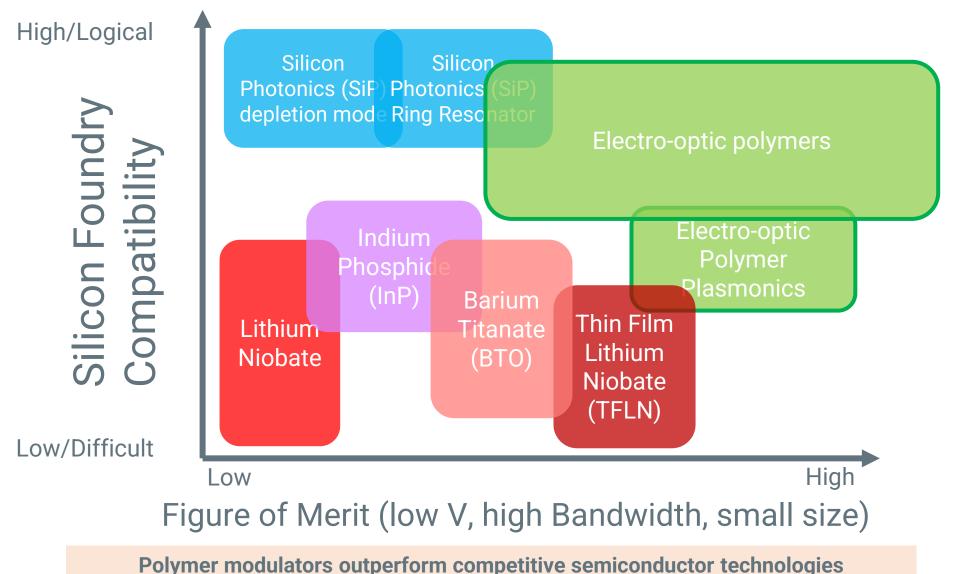
Sources*: KIT, SilOriX, EU Horizon 2020, ETH Zurich, Polariton, CAU University Kiel (post deadline paper published at ECOC2022 using LWLG EO polymers)



EO polymers are competitive with semiconductor modulators...

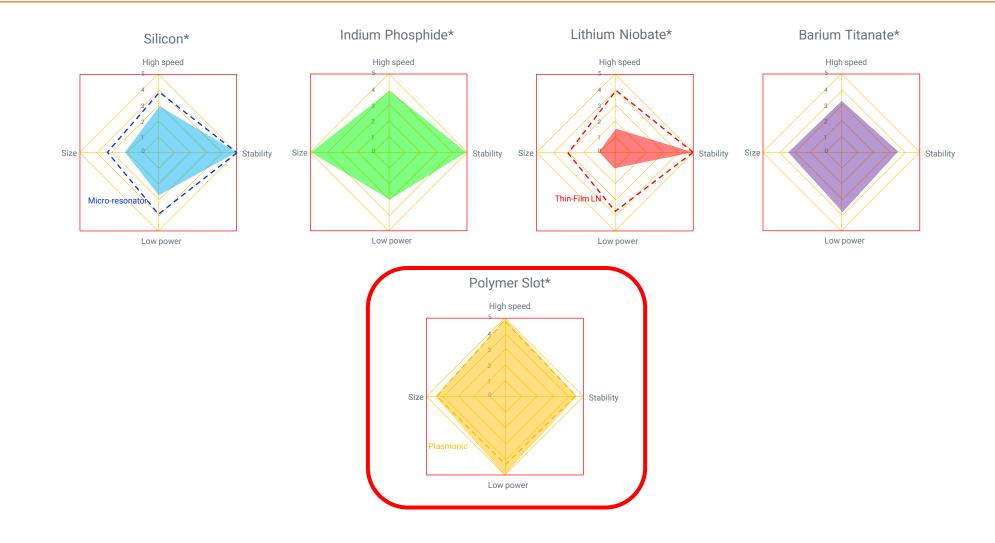
Competitive polymer positioning





Polymer attributes are impressive...

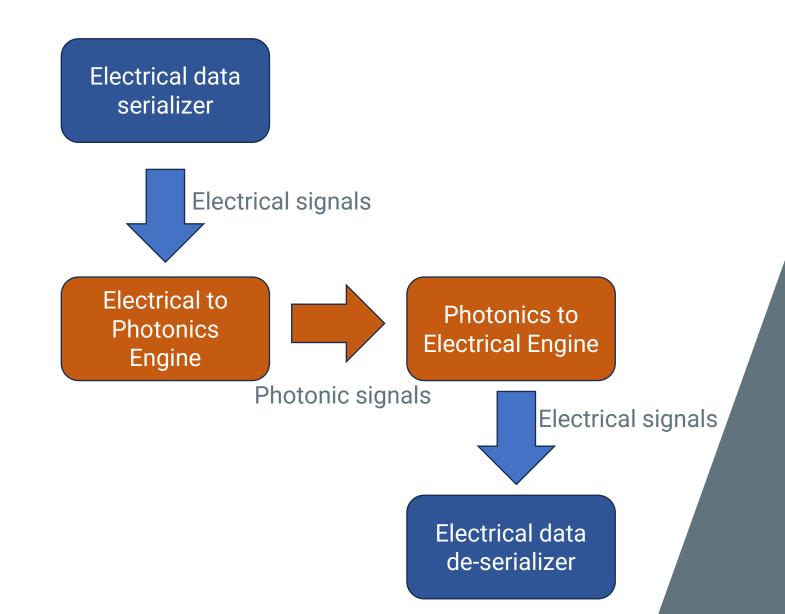




Technology spider chart \rightarrow polymers have strong coverage \rightarrow excellent performance



Data flow...high level issues



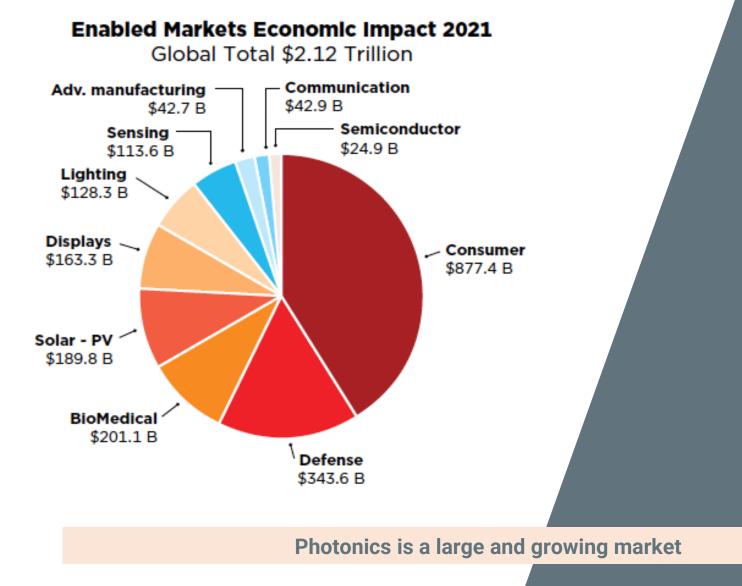
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Electrical signals: high loss per distance, but low loss at interfaces

Photonics signals: low loss per distance, but high loss at interfaces

Enabled photonics market

Enabled markets of photonics



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